

IN THE CLAIMS

Cancel claims 1-163 without prejudice or disclaimer, and add new claim 164 as follows:

164. (New) A fabricating method comprising the steps of:

processing semiconductor wafers by a plurality of processing apparatuses each including at least one processing chamber and an interface having transporting means for transporting a semiconductor wafer to be processed into said processing chamber and for sending out a processed semiconductor wafer, wherein timings of transporting the semiconductor wafers at said interfaces of said processing apparatuses are scheduled according to a predetermined scheduling, and said predetermined scheduling is made by use of a unit time which is common to all of said plurality of processing apparatuses; and

transporting semiconductor wafers from one of the processing apparatuses to another by an inter-apparatus transporter;

wherein, in each of said plurality of processing apparatuses, semiconductor wafers are set at said interface by

said inter-apparatus transporter, transported into said processing chamber by said transporting means, processed in said processing chamber, and transported out of said processing chamber by said transporting means; and

wherein time interval assigned to each of said processing apparatuses including time for transporting a semiconductor wafer to be processed into said processing chamber at said interface, time for processing the semiconductor wafer in said processing chamber, time for transporting the semiconductor wafer out of said processing chamber and sending out at said interface is set a N multiplication of said unit time, with N being a positive integer. |